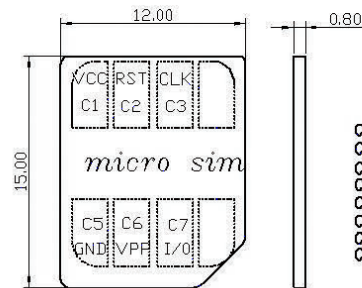
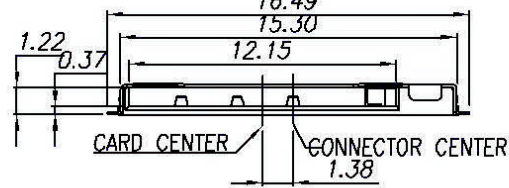
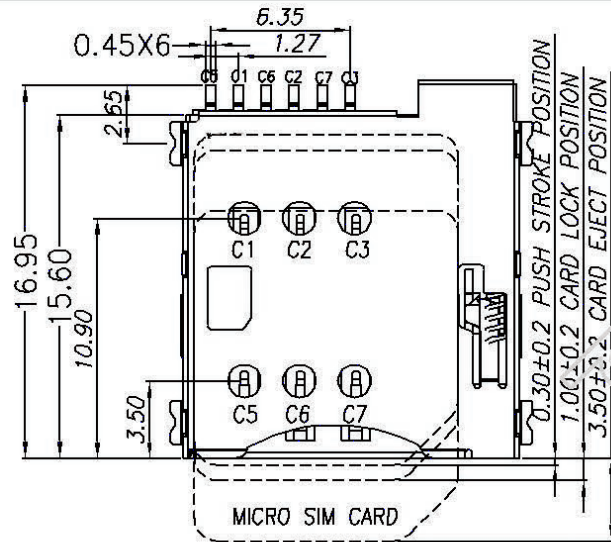


* 所有原材料, 生产制程, 电镀必须符合ROHS要求



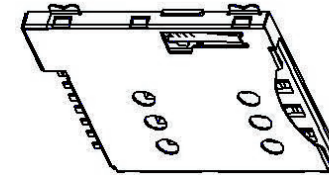
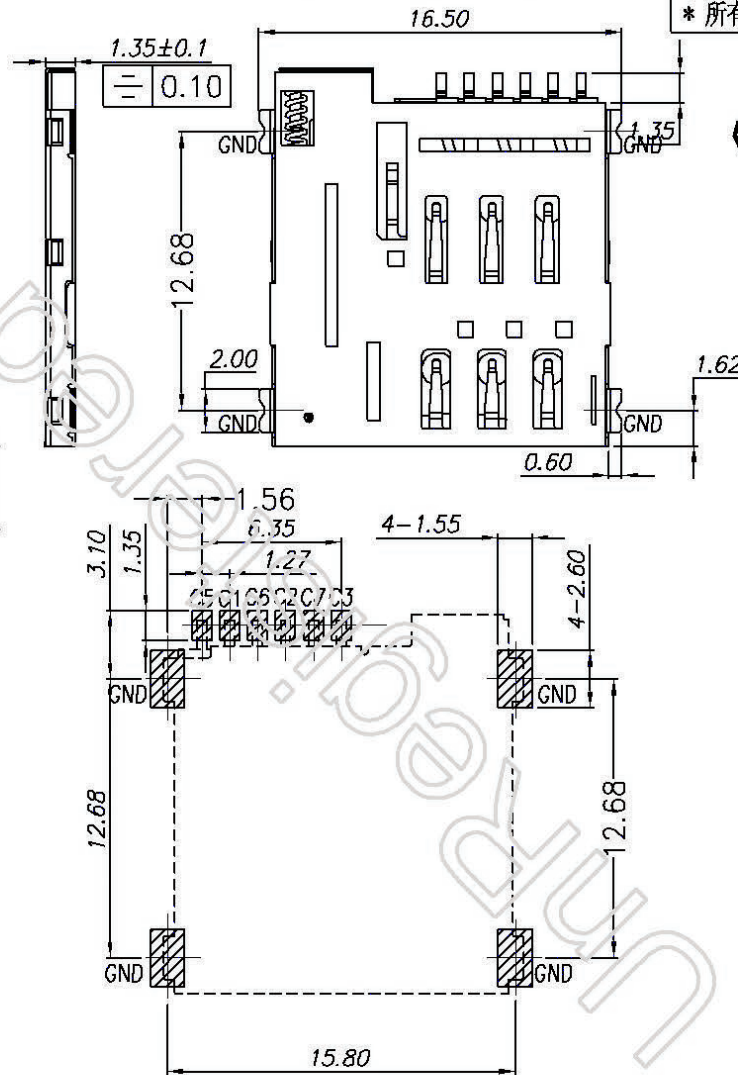
C1:VCC
C2:RST
C3:CLK
C4:RESERVED
C5:GND
C6:VPP
C7:I/O
C8:RESERVED

MICRO SIM CARD

■ CIRCUT TRACE KEEP OUT AREA
■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



Specification

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy

PLATING:

Contact: Plated 50u" Ni Overall Contact Au 1U
Shell: Plated 50u" Ni Overall
Plated 1u" Au Selective Contact Area

Electrical:

Current Rating :0.5mA AC/DC max.
Voltage Rating :125V AC/DC
Ambient Temperature Range :-20° C~+60° C
Storage Temperature Range :-40° C~+70° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100m Ω
Insulation Resistance:1000M Ω min./500VDC
Mating Cycles:10,000 Insertions
产品耐温度: 260° C ~ 150° C

REVISION NO.	REV. NO.	DESCRIPTION	DATE
1			

DIMENSIONS IN: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION TOLERANCE
L.X: ± 0.15
L.XX: ± 0.10
L.XXX: ± 0.06
ANGULAR: ± 1°

PRODUCT NAME:	MICRO-SIM 卡座/PUSH/PUSH 1.35H-6 PIN XMT Edition	DRAWING:	COCO	DATE:	2012/04/10
PRODUCT NO.:	0121AAAA07A	CHECK:	JANY	DATE:	2012/04/11
DRAWING NO.:		APPROVED:	林心祥	DATE:	2012/04/11
SCALE:	1:1	DWG ID:	C D	REV.:	A
				PAGE:	1 of 1